ABSTRACT

The present invention relates to a resin-molded chip solid electrolyte capacitor comprising a plurality of solid electrolyte capacitor elements horizontally laid in parallel with no gap on a pair of oppositely disposed end parts of a lead frame, and a fixing layer which is extending across the plurality of capacitor elements and fixing the capacitor elements with each other; and having low equivalent series resistance (ESR) and low leakage current (LC value), a production method of the same and an electronic device using the capacitor.

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